



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE4206-2G		<b>Issued</b>		26. September 2014		
<b>MA#</b>		MA000727136						
<b>Package</b>		PG-DSO-14-22		<b>Weight*</b>		142.95 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.173	2.22	2.22	22199	22199
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		106	
	non noble metal	zinc	7440-66-6	0.060	0.04		422	
	non noble metal	iron	7439-89-6	1.207	0.84		8443	
wire	non noble metal	copper	7440-50-8	49.007	34.28	35.17	342838	351809
	noble metal	gold	7440-57-5	0.217	0.15	0.15	1519	1519
	encapsulation	organic material	carbon black	1333-86-4	0.172	0.12		1206
plastics	plastics	epoxy resin	-	7.928	5.55		55462	
		inorganic material	silicondioxide	60676-86-0	78.074	54.62	60.29	546179
leadfinish	non noble metal	tin	7440-31-5	1.226	0.86	0.86	8578	8578
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7204	7204
glue	plastics	acrylic resin	-	0.184	0.13		1286	
		noble metal	silver	7440-22-4	0.652	0.46	0.59	4558
*deviation	< 10%				Sum in total:		100.00	1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com